

## Proximity Sensor With VCSEL in Ultra Thin Small Package, I<sup>2</sup>C Interface



#### **LINKS TO ADDITIONAL RESOURCES**

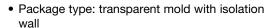




#### **DESCRIPTION**

The VCNL36829UM is a fully integrated proximity sensor. It combines a vertical-cavity surface-emitting laser (VCSEL), photodiode, and application-specific integrated circuit (ASIC) within a ultra thin small package. The VCNL36829UM has been developed for proximity detection applications that offers quite some advanced features including dual slave address, low power consumption, smallest volume package design with isolation wall for the best signal to noise ratio performance with the flexible of mechanical design. In addition, given the typical rated supply voltage of 1.8 V to reduce power consumption, the sensor is intended for battery-powered applications.

#### **FEATURES**





RoHS COMPLIANT HALOGEN

FREE

**GREEN** 

- Dimensions (L x W x H in mm): 1.6 x 1.0 x 0.35
- · Integrated modules: vertical-cavity surfaceemitting laser (VCSEL) and a proximity sensor
- Support both 1.2 V and 1.8 V I<sup>2</sup>C I/O with
- 1.8 V supply voltage
- I2C interface up to 1 MHz (fast mode plus)
- Present on I<sup>3</sup>C bus (spike filter implemented)
- Low power consumption with 5 μA idle current
- · A small package allows a design with a small window size
- Smart dual I<sup>2</sup>C slave address in one package
- Immunity to red glow (940 nm VCSEL)
- Programmable I<sub>VCSEL</sub> sink current
- Intelligent cancellation to reduce cross talk phenomenon
- Smart persistence scheme to reduce measurement response time
- Interrupt functionality
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### **APPLICATIONS**

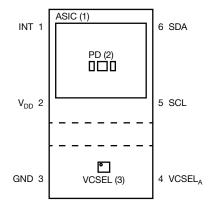
- True wireless stereo (TWS) earbuds
- VR / AR headsets and smart glasses
- · Smart wearables / IOT devices
- · Touchless button / dispensing

PRODUCT SUMMARY									
PART NUMBER	OPERATING RANGE (mm)	OPERATING VOLTAGE RANGE (V)	I <sup>2</sup> C BUS VOLTAGE RANGE (V)	MAX. VCSEL DRIVING CURRENT (mA)	ADC RESOLUTION PROXIMITY / AMBIENT LIGHT				
VCNL36829UM	50	1.65 to 2.00	1.08 to 3.6	18	16 bit / -				

ORDERING INFORMATION									
ORDERING CODE PACKAGING		VOLUME (1)	REMARKS						
VCNL36829UM	Tape and reel	MOQ: 5000 pcs, 5000 pcs/reel	1.6 mm x 1.0 mm x 0.35 mm						

(1) MOQ: minimum order quantity

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PIN DESCRIPTION								
PIN NUMBER	PIN NAME	TYPE	DESCRIPTION					
1	INT	O (open drain)	Interrupt					
2	$V_{DD}$	I	Supply voltage					
3	GND	I	Ground					
4	VCSELA	I	VCSEL anode					
5	SCL (1)	I / O (open drain)	I <sup>2</sup> C serial clock					
6	SDA (1)	I / O (open drain)	I <sup>2</sup> C serial data					

#### Note

<sup>(1)</sup> Pin 5 (SCL) and pin 6 (SDA) can be swapped to change the slave address from 0x60 to 0x51; please refer to Table 1

ABSOLUTE MAXIMUM RATINGS (T <sub>amb</sub> = 25 °C, unless otherwise specified)									
PARAMETER	TEST CONDITION	SYMBOL	MIN.	MAX.	UNIT				
Supply voltage		V <sub>DD</sub>	0	2	V				
Ambient temperature range		T <sub>amb</sub>	-40	+85	°C				
Storage temperature range		T <sub>stg</sub>	-40	+100	°C				



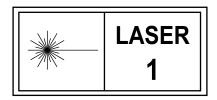
<b>BASIC CHARACTERISTICS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)										
PARAMETER	ARAMETER TEST CONDITION			TYP.	MAX.	UNIT				
ASIC										
Supply voltage		$V_{DD}$	1.65	1.80	2.00	V				
(4)	Shutdown state; light condition = dark; V <sub>DD</sub> = 1.8 V		-	1	-					
Supply current (1)	Idle state <sup>(2)</sup> ; V <sub>DD</sub> = 1.8 V	I <sub>DD</sub>	-	5	-	μA				
	Active state (2); V <sub>DD</sub> = 1.8 V		-	310	-					
I <sup>2</sup> C supply voltage		V <sub>PULL UP</sub>	1.08	1.8	3.6	V				
I <sup>2</sup> C signal input, logic high	V <sub>DD</sub> = 1.8 V	$V_{IH}$	0.9	-	-	V				
I <sup>2</sup> C signal input, logic low	V <sub>DD</sub> = 1.8 V	V <sub>IL</sub>	-	-	0.45	V				
VCSEL										
Supply voltage of the VCSEL (3)		$V_{VCSEL}$	2.8	-	3.6	V				
Forward voltage	I <sub>F</sub> = 9 mA	V <sub>F</sub>	-	2	-	V				
Forward current		I <sub>F</sub>	8	-	18	mA				
Angle of half intensity	FWHM	φ	-	± 4.5	-	0				
Peak wavelength	I <sub>F</sub> = 9 mA	λρ	930	940	955	nm				
Spectral bandwidth	I <sub>F</sub> = 9 mA	Δλ	-	3	-	nm				
PHOTODIODE										
Angle of half sensitivity		φ	-	± 60	-	0				
Peak sensitivity wavelength		$\lambda_{p}$	-	850	-	nm				

#### Notes

- (1) Actual current consumption depends on the register settings. Please refer to the application note on the current consumption
- (2) Excluding VCSEL driving current
- (3) V<sub>VCSEL</sub> should at least match the minimum required supply voltage for the VCSEL V<sub>VCSEL</sub>, min. Please refer to the V<sub>VCSEL</sub>, min table

V <sub>VCSEL</sub> , MIN.						
PS_CURRENT (I <sub>F</sub> )	8 mA	10 mA	12 mA	14 mA	16 mA	18 mA
V <sub>VCSEL, min.</sub>	2.80 V	2.90 V	3.00 V	3.08 V	3.16 V	3.22 V
V <sub>VCSEL, max.</sub>			3.6	6 V		

#### LASER CLASS

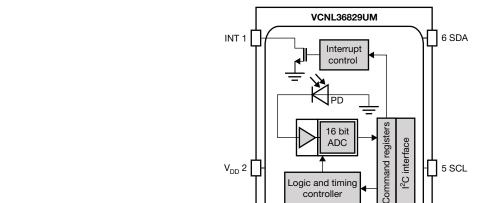


#### Note

• Product specification with IEC / EN 60825-1:2014 compliance and above label

**BLOCK DIAGRAM** 

# Vishay Semiconductors



GND 3

Logic and timing controller

Oscillator

VCSEL

4 VCSEL<sub>A</sub>

**VCSEL** 

driver



I <sup>2</sup> C BUS TIMING CHARACTERISTICS (T <sub>amb</sub> = 25 °C, unless otherwise specified)									
PARAMETER	SYMBOL	STANDARD MODE		FAST	UNIT				
PANAIVIETEN	STIVIBOL	MIN.	MAX.	MIN.	MAX.	UNIT			
Clock frequency	f <sub>(I2CCLK)</sub>	10	100	10	400	kHz			
Bus free time between start and stop condition	t <sub>(BUF)</sub>	4.7	-	1.3	-	μs			
Hold time after (repeated) start condition; after this period, the first clock is generated	t <sub>(HDSTA)</sub>	4.0	-	0.6	-	μs			
Repeated start condition setup time	t <sub>(SUSTA)</sub>	4.7	-	0.6	-	μs			
Stop condition setup time	t <sub>(SUSTO)</sub>	4.0	-	0.6	-	μs			
Data hold time	t <sub>(HDDAT)</sub>	0	3450	0	900	ns			
Data setup time	t <sub>(SUDAT)</sub>	250	-	100	-	ns			
I <sup>2</sup> C clock (SCL) low period	t <sub>(LOW)</sub>	4.7	-	1.3	-	μs			
I <sup>2</sup> C clock (SCL) high period	t <sub>(HIGH)</sub>	4.0	-	0.6	-	μs			
Clock / data fall time	t <sub>(f)</sub>	=	300	-	300	ns			
Clock / data rise time	t <sub>(r)</sub>	-	1000	-	300	ns			

#### Note

Data based on standard I<sup>2</sup>C protocol requirement, not tested in production

I<sup>2</sup>C BUS DATA (SDA)

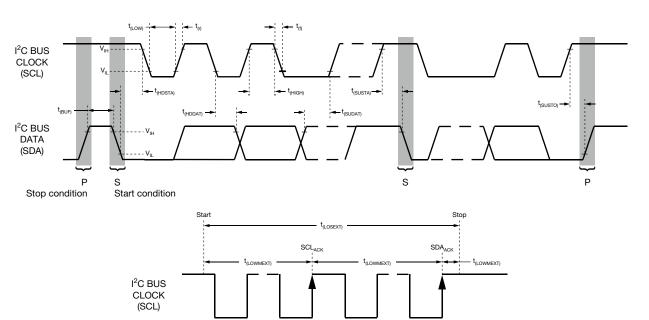


Fig. 1 - I<sup>2</sup>C Bus Timing Diagram

#### PARAMETER TIMING INFORMATION

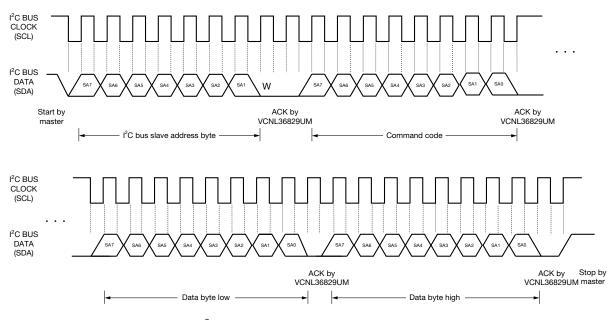


Fig. 2 - I<sup>2</sup>C Bus Timing for Sending Word Command Format

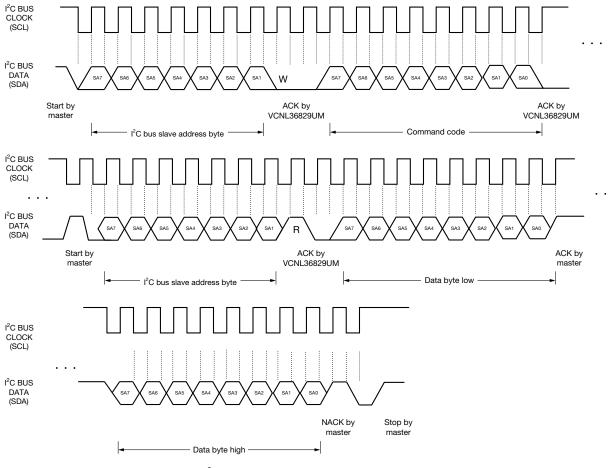


Fig. 3 - I<sup>2</sup>C Bus Timing for Receiving Word Command Format

### TYPICAL PERFORMANCE CHARACTERISTICS (T<sub>amb</sub> = 25 °C, unless otherwise specified)

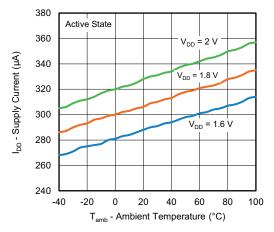


Fig. 4 - Supply Current vs. Ambient Temperature

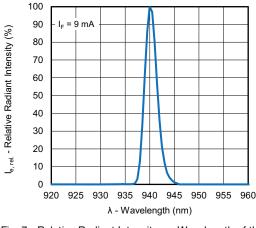


Fig. 7 - Relative Radiant Intensity vs. Wavelength of the VCSEL

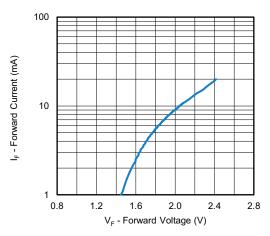


Fig. 5 - Forward Current vs. Forward Voltage of the VCSEL

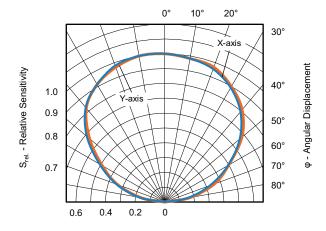


Fig. 8 - Relative Sensitivity vs. Angular Displacement of the Photodiode

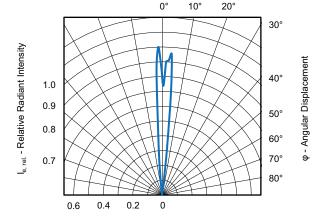


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement of the VCSEL

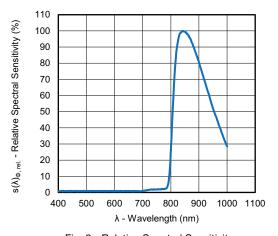


Fig. 9 - Relative Spectral Sensitivity vs. Wavelength of the Photodiode





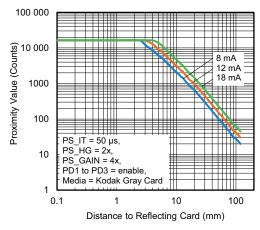


Fig. 10 - Proximity Value vs. Distance (IT = 2T)

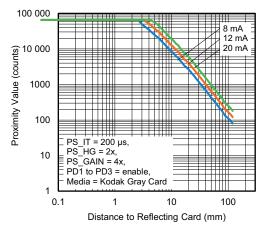


Fig. 11 - Proximity Value vs. Distance (IT = 8T)

#### **APPLICATION INFORMATION**

#### **Slave Address Selection**

The VCNL36829UM supports a smart dual slave address where the designer can change the slave address by swapping the SCL and SDA pins, as shown in Table 1.

TABLE 1 - SLAVE ADDRESS TABLE									
PIN 5	PIN 6	7 BIT SLAVE ADDRESS	8 BIT SLAVE ADDRESS (WRITE)	8 BIT SLAVE ADDRESS (READ)					
SCL	SDA	0x60	0xC0	0xC1					
SDA	SCL	0x51	0xA2	0xA3					

A smart dual slave address provides the flexibility for the designer to connect two devices from two different slave addresses on the same I<sup>2</sup>C bus. Besides that, the two slave address options allow designers to select a different slave address if one is used by the other slave devices on the same I<sup>2</sup>C bus in a single device application.

To ensure more stable slave address recognition, especially in systems with higher noise levels, it is recommended to follow a specific power-on sequence: apply power to the  $I^2$ C bus first, followed by  $V_{DD}$ . This sequence helps the IC determine the correct slave address more reliably in noisy environments.

#### Application Circuit With a Single Device - Slave Address 0x60

Fig. 12 shows an application circuit example with a single device. As described in Table 1, when pins 5 and 6 are connected to the clock and data signal from the microcontroller, as shown in Fig. 12, they will then be configured as an SCL pin and SDA pin, respectively. The 7 bit slave address option of 0x60 will be automatically selected.

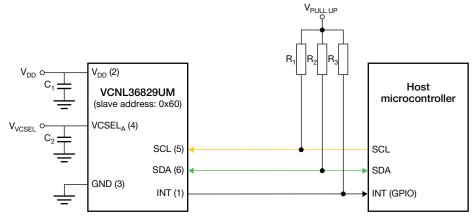


Fig. 12 - Application Circuit Example for a Single VCNL36829UM - Slave Address 0x60

#### Application Circuit With a Single Device - Slave Address 0x51

On the other hand, when pins 5 and 6 are connected to the data and clock signal from the microcontroller, as shown in Fig. 13, they will then be configured as an SDA pin and SCL pin, respectively. The 7 bit slave address option of 0x51 will be automatically selected.

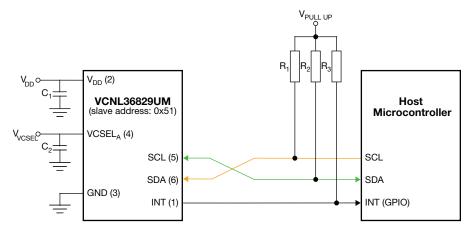


Fig. 13 - Application Circuit Example for a Single VCNL36829UM - Slave Address 0x51

Table 2 shows the required values and the explanation for the individual application circuit parameters.

IADLE 2 - A	PPLICATION	CIRCUIT PARAMETERS
CIRCUIT PARAMETER	VALUE	DESCRIPTION
$V_{DD}$	1.65 V to 2.00 V	A stable power supply such as a low dropout regulator or a switching regulator is required; the power supply isolation can be further improved with a decoupling capacitor C <sub>1</sub>
$V_{VCSEL}$	2.80 V to 3.60 V	A stable power supply such as a low dropout regulator or a switching regulator that can supply an adequate amount of power (max. VCSEL pulse driving current of 18 mA) is required; the power supply isolation can be further improved with a decoupling capacitor C <sub>2</sub> ; the minimum voltage depends on the selected driving current of the VCSEL; please refer to Table V <sub>VCSEL, min.</sub> for reference
V <sub>PULL UP</sub>	1.2 V to 3.6 V	A stable power supply such as a low dropout regulator or a switching regulator is required; a voltage level shifter is required if the I <sup>2</sup> C bus voltage from the microcontroller is higher than 3.6 V
C <sub>1</sub> - C <sub>4</sub>	100 nF to 1 μF	Decoupling capacitors are recommended to reduce the noise in the supply voltage
R <sub>1</sub> - R <sub>2</sub>	2.2 kΩ to 4.7 kΩ	Pull-up resistors within the range of 2.2 k $\Omega$ to 4.7 k $\Omega$ are recommended; any increase in bus capacitance or resistance will increase the logic high transition time
R <sub>3</sub>	$4.7~\text{k}\Omega$ to $22~\text{k}\Omega$	Pull-up resistor within the range of 4.7 k $\Omega$ to 22 k $\Omega$ is recommended

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#### **Application Circuit With a Smart Dual Slave Address**

Fig. 14 shows an application circuit example with a smart dual slave address. By swapping the SCL and SDA pins of the second device, as shown in Table 1, the designer can change the 7 bit slave address of the VCNL36829UM. This provides the flexibility for the designer to connect two devices from two different slave addresses on the same I<sup>2</sup>C bus.

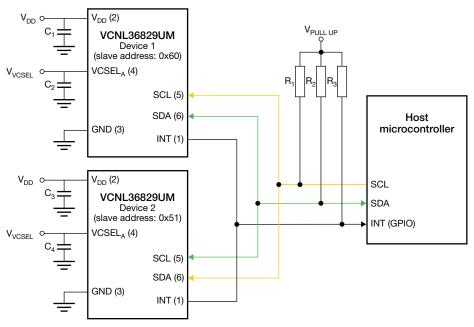


Fig. 14 - Application Circuit Example for Two VCNL36829UMs - Smart Dual Slave Address

#### I<sup>2</sup>C Write and Read Protocol

The communication with the VCNL36829UM can be performed via I<sup>2</sup>C. The I<sup>2</sup>C write and read protocol when communicating with the proximity sensor is shown in Fig. 15.

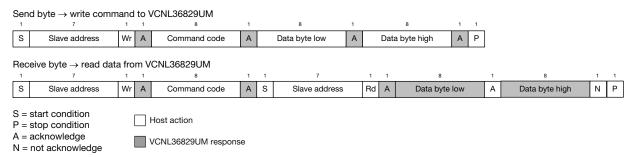


Fig. 15 - I2C Write and Read Protocol

It is imperative that only the restart condition for the I2C read is implemented instead of the stop and restart condition.



#### **Function Description**

COMMAND CODE	DATA BYTE LOW / HIGH	REGISTER NAME	DEFAULT VALUE	FUNCTION	ACCESS			
						Internal calibration setting		
	L	PS_CONF1_L	0x00	Active force mode trigger setting				
0.00				Switch the sensor on / off				
0x00				Interrupt setting				
	Н	PS_CONF1_H	0x01	Persistence setting				
				Shutdown setting				
0x01	L	PS_CONF2_L	0x00	Wait time setting				
UXUT	Н	PS_CONF2_H	0x00	Integration time setting				
0x02	L	PS_CONF3_L	0x00	VCSEL driving current setting				
UXU2	Н	PS_CONF3_H	0x00	High gain setting	Write and			
0x03	L	PS_CONF4_L	0x00	Reserved	read			
UXUS	Н	PS_CONF4_H	0x00	Sunlight cancellation setting				
0x04	L	PS_THDL_L	0x00	Low threshold interrupt value setting (low byte)				
0X04	Н	PS_THDL_H	0x00	Low threshold interrupt value setting (high byte)				
0x05	L	PS_THDH_L	0x00	High threshold interrupt value setting (low byte)				
UXUS	Н	PS_THDH_H	0x00	High threshold interrupt value setting (high byte)				
0x06	L	PS_CANC_L	0x00	Offset count cancellation value setting (low byte)				
UXUO	Н	PS_CANC_H	0x00	Offset count cancellation value setting (high byte)				
0x08	L	PS_CONF5_L	0x00	Reserved (must be set to 0xA0)				
UXUO	Н	PS_CONF5_H	0x00	Reserved				
0xF8	L	PS_DATA_L	0x00	Proximity output data (low byte)				
UXFO	Н	PS_DATA_H	0x00	Proximity output data (high byte)				
050	L	Reserved	0x00 to 0xFF	Reserved				
0xF9	Н	INT_FLAG	0x00	PS interrupt flag	Read			
	L	VCNL36829UM_ID_L	0x29	Device ID	only			
0xFA	Н	VCNL36829UM_ID_H	0x00 / 0x10	Device ID <sup>(1)</sup> Slave address: 0x60; ID = 0x00 Slave address: 0x51; ID = 0x10				

#### Notes

<sup>•</sup> All of the reserved registers are used for internal test. These values must be kept constant.

<sup>(1)</sup> The default ID depends on the connection of the SCL and SDA pins on the VCNL36829UM with the SCL and SDA pins on the host MCU. If pins 5 and 6 on the VCNL36829UM are connected to the SCL and SDA pins on the host, the default value will be 0x00. On the other hand, if pins 5 and 6 on the VCNL36829UM are connected to the SDA and SCL pins on the host, the default value will be 0x10. Please refer to Fig. 13.



#### **Command Register Format**

TABLE 4	TABLE 4 - REGISTER NAME: PS_CONF1_L									
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
PS_CAL	Reserved	PS_TRIG	PS_MODE		Reserved		PS_ON			
COMMAND	CODE					0x00				
Bit N	lame	Fund	tion	Bit	Value	Descri	ption			
DC	CAL	Enable / disable the	internal calibration	7	0x0 (0b0)	Disable (	default)			
F3_	CAL	Enable / disable the internal calibration		/	0x1 (0b1)	Enal	ole			
Rese	erved	Reserved		6	0x0 (0b0)	Should be kept default				
		Set the active force mode trigger;			0x0 (0b0)	Off (default)				
PS_	TRIG	This bit will be reset to 0 after 5 the measurement cycle		0x1 (0b1)	Trigo	ger				
DC N	/ODE	Set the measu	rement mode	4	0x0 (0b0)	Auto Mode (default)				
F3_IV	NODE	of the	sensor	4	0x1 (0b1)	Active force mode				
Rese	erved	Rese	Reserved 3:1 0x0 (0b0		0x0 (0b000)	Should be k	ept default			
PS_ON		Switch the sensor on / off		0	0x0 (0b0)	Turn off th (shutdown)				
					0x1 (0b1)	Turn on the sensor				

TABLE 5	TABLE 5 - REGISTER NAME: PS_CONF1_H									
Bit 15	Bit 14	Bit 13 Bit 12		Bit 11	Bit 10	Bit 9	Bit 8			
PS_	PS_INT PS_PERS PS_SN			PS_SMART_PERS	PS_SP_INT	PS_START_INT	PS_SD			
COMMAND	CODE					0x00				
Bit N	ame	Fund	tion	Bit	Value	Descri	otion			
					0x0 (0b00)	Interrupt disal	ole (default)			
					0x1 (0b01)	Logic High/I	_ow mode			
PS_	INT	Set the interrupt mode setting		15 : 14	0x2 (0b10)	First h	igh			
					0x3 (0b11)	Trigger by each high/low threshold event				
		Set the amount of consecutive threshold crossing events necessary to trigger interrupt			0x0 (0b00)	1 time (default)				
PS_F	DEDO			13 : 12	0x1 (0b01)	2 times				
F3_F	TENO				0x2 (0b10)	3 times				
					0x3 (0b11)	4 times				
		Enable / disable the	•		0x0 (0b0)	Disable (d	lefault)			
PS_SMAF	RT_PERS	setting when the interrupt event is triggered		11	0x1 (0b1)	Enable				
PS_SF	D INIT	Enable / disable the	sunlight protection	10	0x0 (0b0)	Disable (d	lefault)			
F3_3r	!!\	mode inter	rupt setting	10	0x1 (0b1)	Enable				
PS STA	PS START INT  After PS_SD disable, PS 1st detection		9	0x0 (0b0)	Disable (d	default)				
10_017		Interrupt en	able setting	J	0x1 (0b1)	Enab	ole			
PS	SD.	PS shutdown setting		8	0x0 (0b0)	Disab	ole			
PS_SD		FS shutdown setting			0x1 (0b1)	Enable (default)				

TABLE 6 -	TABLE 6 - REGISTER NAME: PS_CONF2_L									
Bit 7         Bit 6         Bit 5         Bit 4         Bit 3         Bit 2         Bit 1         Bit 0										
	PS_WAIT									
COMMAND CO	DDE					0x01				
Bit N	Bit Name Function Bit Value Description									
PS_\	WAIT	PS wait time after PS detection 7:0			0 to 254 2.5 ms x (PS_WAIT + 1)					



TABLE 7 - REGISTER NAME: PS_CONF2_H											
Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8				
Reserved PS_IT											
COMMAND C	COMMAND CODE 0x01										
Bit N	lame	Function		Bit	Value	Descr	iption				
Rese	erved	Rese	erved 15 : 12		0x0 (0b0000)	(0b0000) Should be kept de					
DC IT		Set the integration time		11:8	0x0 (0b0000)	12.5 µs (default)					
PS_IT		for one me	asurement	11.0	1 to 15	25 μs x PS_IT					

TABLE 8 -	REGISTER	NAME: PS_CO	NF3_L				
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	R	eserved		PS_CURRENT_EN	PS_CURRENT		
COMMAND C	ODE					0x02	
Bit Name Function			ction	Bit	Value	Desci	ription
Rese	erved	Rese	erved	7:4	0x0 (0b0000)	Should be l	kept default
PS_CURRENT_EN		VCCEL driver	anable actting	3	0x0 (0b0)	Disable (default)	
		VCSEL driver enable setting		9	0x1 (0b1)	Ena	able
					0x0 (0b000)	Reserved	d (default)
					0x1 (0b001)	Reserved	
					0x2 (0b010)	8 mA	
DC CU	IDDENIT	Cat the VCCTI	duisting assument	2:0	0x3 (0b011)	10 mA	
P5_C0	IRRENT	Set the voset	driving current	2:0	0x4 (0b100)	12 mA	
					0x5 (0b101)	14	mA
					0x6 (0b110)	16	mA
					0x7 (0b111)	18	mA

TABLE 9 -	REGISTER I	NAME: PS_CO	NF3_H				
Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
Reserved	PS_HG	PS_GAIN		Reserved	PD3_EN	PD2_EN	PD1_EN
COMMAND C	ODE					0x02	
Bit N	Bit Name Function		ction	Bit	Value	Descr	iption
Rese	erved	Rese	erved	15	0x0 (0b0)	Should be I	kept default
DC	HG	Sot the gain	of the ADC	14	0x0 (0b0)	x1 gain	(default)
F-3_	_rid	Set the gain of the ADC		14	0x1 (0b1)	x2	gain
					0x0 (0b00)	x4 gain (default)	
DS (	GAIN	Set the gain of the ADC		13 : 12	0x1 (0b01)	x2 (	gain
F3_(	JAIN				0x2 (0b10)	x1 (	gain
					0x3 (0b11)	Reserved	
Rese	erved	Rese	erved	11	0x0 (0b0)	Should be I	kept default
DD3	S EN	DD2 onak	ole setting	10	0x0 (0b0)	Disable	(default)
	<b>0_</b> ∟IN	FD3 enak	ne setting	10	0x1 (0b1)	Enable	
DDO	ENI	DD2 anak	olo cotting	9	0x0 (0b0)	Disable	(default)
PD2_EN		PD2 enable setting		9	0x1 (0b1)	Enable	
DD1	EN	PD1 enable setting		8	0x0 (0b0)	Disable (default)	
PDI		PDT enak	ne setting	0	0x1 (0b1)	Ena	able



TABLE 10	TABLE 10 - REGISTER NAME: PS_CONF4_L										
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0				
	Reserved										
COMMAND C	ODE					0x03					
Bit N	Bit Name Function Bit Value Description										
Reserved Reserved 7:0 0x0 (0b00000000) Should be kept defar						cont defect					

TABLE 11 - REGISTER NAME: PS_CONF4_H										
Bit 15	Bit 14	Bit 13	Bit 12	Bit 10	Bit 9	Bit 8				
	Re	eserved		PS_S	SC_LEVEL	PS_SC	Reserved			
COMMAND CODE 0x03										
Bit N	lame	Fund	ction	Bit	Value	Descr	ription			
Reserved Reserved				15 : 12	0xF (0b1111)	Should be I	kept default			
		Sunlight cancellation level setting			0x0 (0b00)	Level 1	(default)			
DC CC	LEVEL			11 : 10	0x1 (0b01)	Lev	el 2			
P3_30	_LEVEL				0x2 (0b10)	Level 3				
					0x3 (0b11)	Level 4				
DC	SC	Enable / disable		9	0x0 (0b0)	Disable (default)				
P5.	_30	the sunlight	the sunlight cancellation		0x1 (0b1)	Enable				
Rese	Reserved Reserved 8 0x0 (0b0) Should be kept				kept default					

TABLE 12	TABLE 12 - REGISTER NAME: PS_THDL									
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
PS_THDL_L										
Bit 15 Bit 14 Bit 13 Bit 12 Bit 11 Bit 10 Bit 9 Bit 8										
	PS_THDL_H									
COMMAND C	ODE					0x04				
Bit N	lame	Fu	ınction	Bit	Value	Desci	ription			
PS_THDL_L			chold interrupt value	7:0	Low byte		byte			
PS_TI	HDL_H	Set the low threshold interrupt value 15:8		15 : 8	0 to 65 535	High byte				

TABLE 13	TABLE 13 - REGISTER NAME: PS_THDH										
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0				
	PS_THDH_L										
Bit 15 Bit 14 Bit 13 Bit 12 Bit 11 Bit 10 Bit 9 Bit 8											
	PS_THDH_H										
COMMAND C	ODE					0x05					
Bit N	lame	Fu	ınction	Bit	Value	Desci	ription				
PS_THDH_L		schold interrupt value	7:0	0 to 65 535	Low	byte					
PS_TH	HDH_H	Set the high threshold interrupt value		15:8	0 10 03 333	High byte					



TABLE 14 - REGISTER NAME: PS_CANC									
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
PS_CANC_L									
Bit 15 Bit 14 Bit 13 Bit 12 Bit 11 Bit 10 Bit 9 Bit 8									
	Reserved PS_CANC_H								
COMMAND C	ODE					0x06			
Bit N	Name	Fund	ction	Bit	Value	Descr	iption		
PS_C	PS_CANC_L Set the offset		7:0	0 to 4095		byte			
PS_C	PS_CANC_H count cancellation value			11:8	0 10 4095	High byte			
Res	Reserved Reserved 15:12 0x0 (0b0000) Should be kept default					kept default			

TABLE 15 - REGISTER NAME: PS_CONF5										
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
Reserved										
Bit 15 Bit 14 Bit 13 Bit 12 Bit 11 Bit 10 Bit 9 Bit 8										
Reserved										
COMMAND C	ODE					0x08				
Bit N	lame	Fund	tion	Bit	Value	Desci	ription			
Rese	erved	Rese	erved	7:4	0x0 (0b0000)	Must be set to	"0xA (0b1010)"			
Reserved Reserved				3:0	0x0 (0b0000)	Should be kept default				
Reserved Reserved 15 : 8 0x0 (0b00000000) Should be kept default							kept default			

TABLE 16	TABLE 16 - REGISTER NAME: PS_DATA									
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			
	PS_DATA_L									
Bit 15 Bit 14 Bit 13 Bit 12 Bit 11 Bit 10 Bit 9 Bit 8										
			PS	S_DATA_H						
COMMAND C	ODE					0xF8				
Bit N	Bit Name Function			Bit	Value	Description				
PS_D	PS_DATA_L Bood the previous custout date		7:0	0 to 65 535	Low byte					
PS_DATA_H Read the proximity output data				15 : 8	0 10 00 000	High	byte			

TABLE 17	TABLE 17 - REGISTER NAME: INT_FLAG											
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0					
			I	Reserved								
Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8					
Reserved				PS_START_FLAG	PS_SPFLAG	PS_IF_CLOSE	PS_IF_AWAY					
COMMAND (	CODE					0xF9						
Bit Name Function				Bit	Value	Descr	iption					
Res	Reserved Reserved		erved	7:0	0x00 - 0xFF (0b00000000 - 0b11111111)	Should be I	kept default					
Res	erved	Rese	erved	15 : 12	0x0 (0b0000)	Should be I	kept default					
DC CTA	RT_FALG	PS finish 1 <sup>st</sup> detection after SD disable		11 -	0x0 (0b0)	No 1st det	ection flag					
F3_31A	INT_FALG				0x1 (0b1)	Finish 1st de	etection flag					
DQ Q	PFLAG	Read the sunlight protection		10	0x0 (0b0)	No sunlight protection mode fla						
1 3_3	ITEAG	mode interru	pt event flag	10	0x1 (0b1)	Sunlight protect	tion mode flag					
DQ IE	CLOSE	Read the hig		9	0x0 (0b0)		hold crossing event flag					
PS_IF_CLOSE		crossing interi	upt event flag	9	0x1 (0b1)	High threshold crossing interrup event flag						
DQ IE	PS_IF_AWAY		eshold crossing	8	0x0 (0b0)	No low threst interrupt	nold crossing event flag					
F3_IF	_AVVA I	interrupt (	event flag	0	0x1 (0b1)	Low threshold crossing interrul						

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TABLE 18	- REGISTER	R NAME: VCN	IL36829UM ID					
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
			VCNL368291	JM_ID_L	•			
Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	
			VCNL36829L	JM_ID_H				
COMMAND C	ODE				0xFA			
Bit	Name	Fu	nction	Bit	Value	Description		
VCNL36829UM_ID_L  VCNL36829UM_ID_H		Read the device ID		7:0	0x29 (0b00101001)	Should be kept default		
				45.0	(0b0000000)		n a slave address of 0x60	
				15 : 8	0x10 (0b00010000)	Device with a slave address of 0x51		

#### **PACKAGE INFORMATION** in millimeters

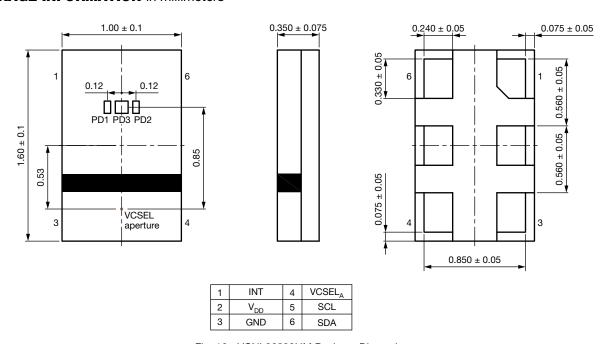


Fig. 16 - VCNL36829UM Package Dimensions



#### **RECOMMENDED LAYOUT PAD INFORMATION** in millimeters

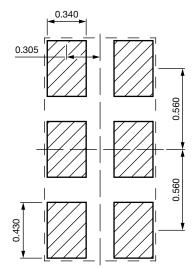


Fig. 17 - VCNL36829UM PCB Layout Footprint

#### **RECOMMENDED INFRARED REFLOW**

Soldering conditions which are based on J-STD-020C

IR REFLOW PROFILE CONDITION								
PARAMETER	CONDITIONS	TEMPERATURE	TIME					
Peak temperature		260 °C + 5 °C / - 5 °C (max.: 265 °C)	10 s					
Preheat temperature range and timing		150 °C to 200 °C	60 s to 180 s					
Timing within 5 °C to peak temperature		-	10 s to 30 s					
Timing maintained above temperature / time		217 °C	60 s to 150 s					
Timing from 25 °C to peak temperature		-	8 min (max.)					
Ramp-up rate		3 °C/s (max.)	=					
Ramp-down rate		6 °C/s (max.)	-					

Recommend normal solder reflow is 235 °C to 265 °C

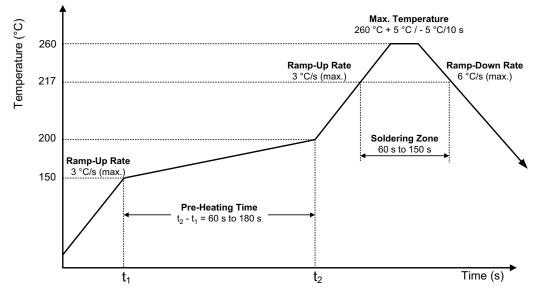
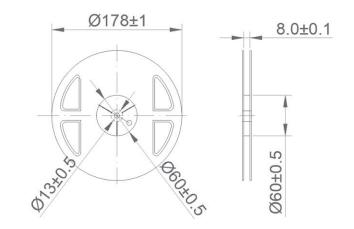
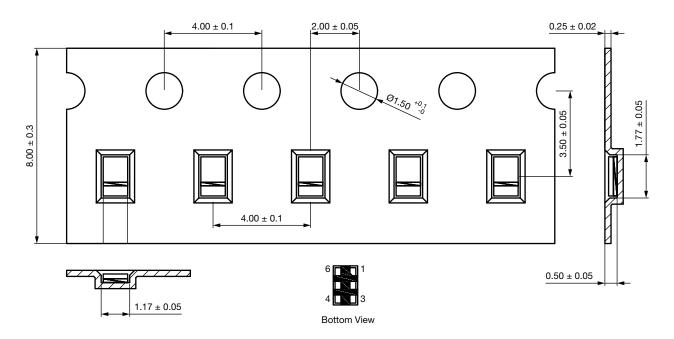


Fig. 18 - VCNL36829UM Solder Reflow Profile Chart

#### TAPE PACKAGING INFORMATION in millimeters







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